

# RJK0348DSP

## Silicon N Channel Power MOS FET Power Switching

REJ03G1644-0201

Rev.2.01

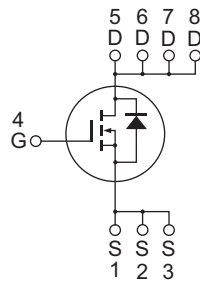
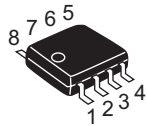
Apr 24, 2008

### Features

- Capable of 4.5 V gate drive
- Low drive current
- High density mounting
- Low on-resistance  
 $R_{DS(on)} = 2.6 \text{ m}\Omega$  typ. (at  $V_{GS} = 10 \text{ V}$ )
- Pb-free

### Outline

RENESAS Package code: PRSP0008DD-D  
(Package name: SOP-8<FP-8DAV>)



1, 2, 3 Source  
4 Gate  
5, 6, 7, 8 Drain

### Absolute Maximum Ratings

( $T_a = 25^\circ\text{C}$ )

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{DSS}$	30	V
Gate to source voltage	$V_{GSS}$	$\pm 20$	V
Drain current	$I_D$	22	A
Drain peak current	$I_{D(pulse)}$ <sup>Note 1</sup>	176	A
Body-drain diode reverse drain current	$I_{DR}$	22	A
Avalanche current	$I_{AP}$ <sup>Note 2</sup>	22	A
Avalanche energy	$E_{AR}$ <sup>Note 2</sup>	48.4	mJ
Channel dissipation	$P_{ch}$ <sup>Note 3</sup>	2.5	W
Channel to ambient thermal impedance	$\theta_{ch-a}$ <sup>Note 3</sup>	50	$^\circ\text{C}/\text{W}$
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Notes: 1.  $PW \leq 10 \mu\text{s}$ , duty cycle  $\leq 1\%$

2. Value at  $T_{ch} = 25^\circ\text{C}$ ,  $R_g \geq 50 \Omega$

3. When using the glass epoxy board (FR4 40 x 40 x 1.6 mm),  $PW \leq 10\text{s}$

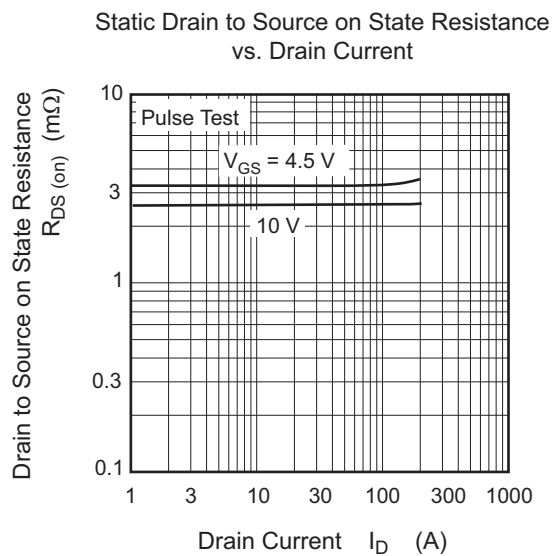
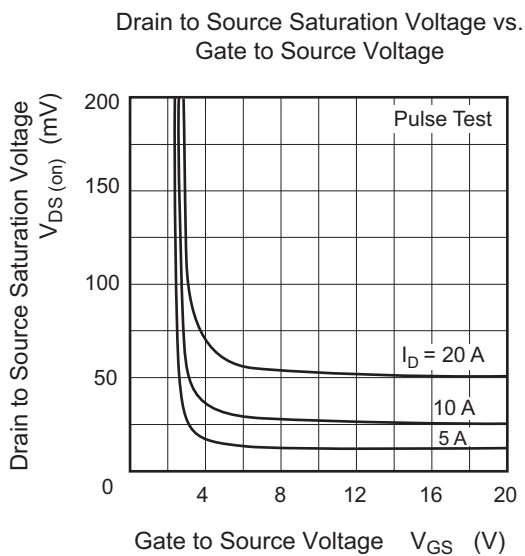
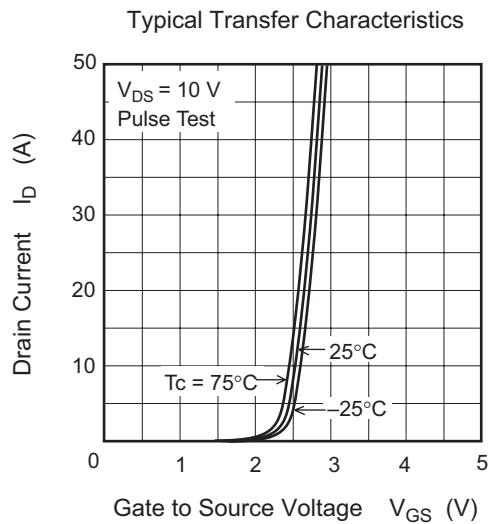
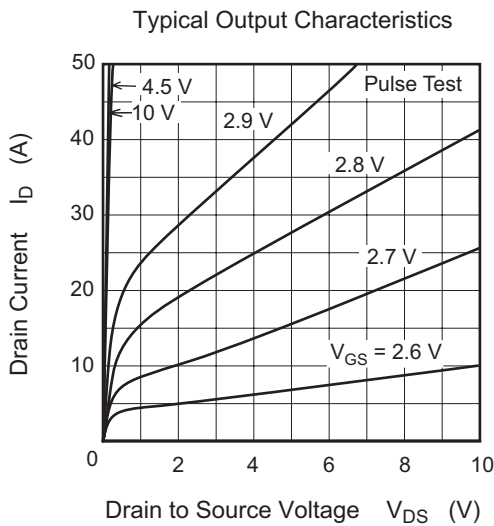
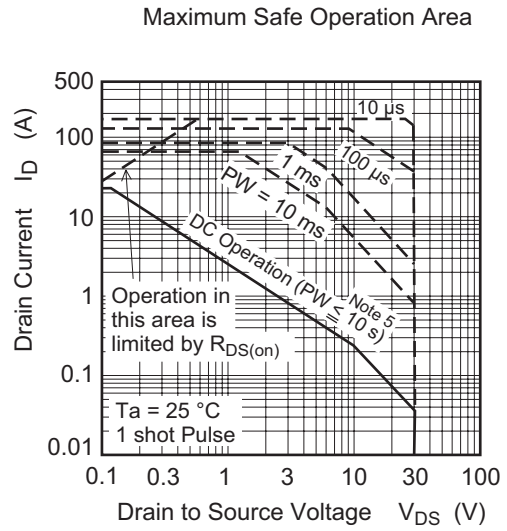
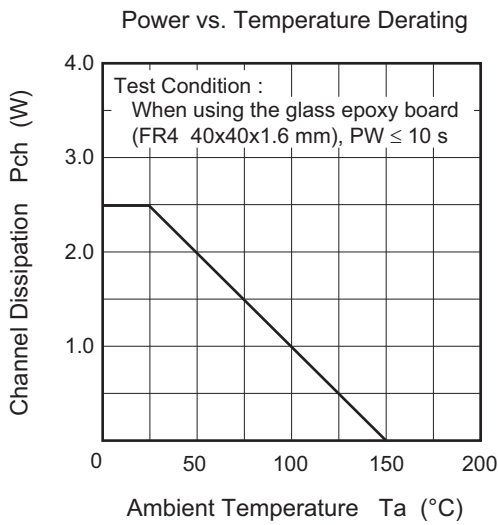
## Electrical Characteristics

(Ta = 25°C)

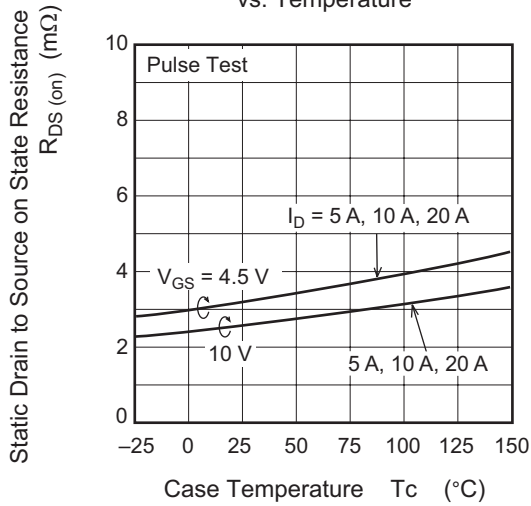
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 10 \text{ mA}$ , $V_{GS} = 0$
Gate to source leak current	$I_{GSS}$	—	—	$\pm 0.1$	$\mu\text{A}$	$V_{GS} = \pm 20 \text{ V}$ , $V_{DS} = 0$
Zero gate voltage drain current	$I_{DSS}$	—	—	1	$\mu\text{A}$	$V_{DS} = 30 \text{ V}$ , $V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.2	—	2.5	V	$V_{DS} = 10 \text{ V}$ , $I_D = 1 \text{ mA}$
Static drain to source on state resistance	$R_{DS(on)}$	—	2.6	3.4	$\text{m}\Omega$	$I_D = 11 \text{ A}$ , $V_{GS} = 10 \text{ V}$ <sup>Note4</sup>
	$R_{DS(on)}$	—	3.2	4.5	$\text{m}\Omega$	$I_D = 11 \text{ A}$ , $V_{GS} = 4.5 \text{ V}$ <sup>Note4</sup>
Forward transfer admittance	$ y_{fs} $	—	60	—	S	$I_D = 11 \text{ A}$ , $V_{DS} = 10 \text{ V}$ <sup>Note4</sup>
Input capacitance	$C_{iss}$	—	5100	—	pF	$V_{DS} = 10 \text{ V}$
Output capacitance	$C_{oss}$	—	980	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	$C_{rss}$	—	315	—	pF	$f = 1 \text{ MHz}$
Gate Resistance	$R_g$	—	1.4	—	$\Omega$	
Total gate charge	$Q_g$	—	34	—	nC	$V_{DD} = 10 \text{ V}$
Gate to source charge	$Q_{gs}$	—	12.5	—	nC	$V_{GS} = 4.5 \text{ V}$
Gate to drain charge	$Q_{gd}$	—	7.0	—	nC	$I_D = 22 \text{ A}$
Turn-on delay time	$t_{d(on)}$	—	13	—	ns	$V_{GS} = 10 \text{ V}$ , $I_D = 11 \text{ A}$
Rise time	$t_r$	—	5.8	—	ns	$V_{DD} \cong 10 \text{ V}$
Turn-off delay time	$t_{d(off)}$	—	69	—	ns	$R_L = 0.91 \Omega$
Fall time	$t_f$	—	10	—	ns	$R_g = 4.7 \Omega$
Body–drain diode forward voltage	$V_{DF}$	—	0.78	1.02	V	$I_F = 22 \text{ A}$ , $V_{GS} = 0$ <sup>Note4</sup>
Body–drain diode reverse recovery time	$t_{rr}$	—	35	—	ns	$I_F = 22 \text{ A}$ , $V_{GS} = 0$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Notes: 4. Pulse test

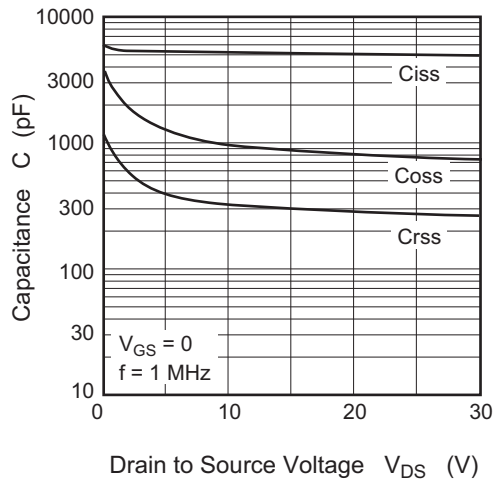
Main Characteristics



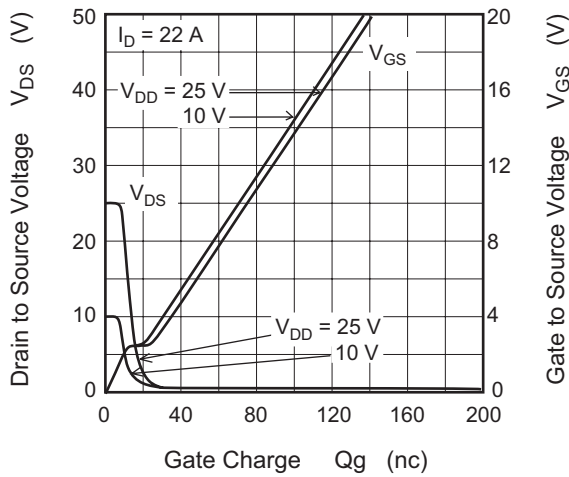
Static Drain to Source on State Resistance vs. Temperature



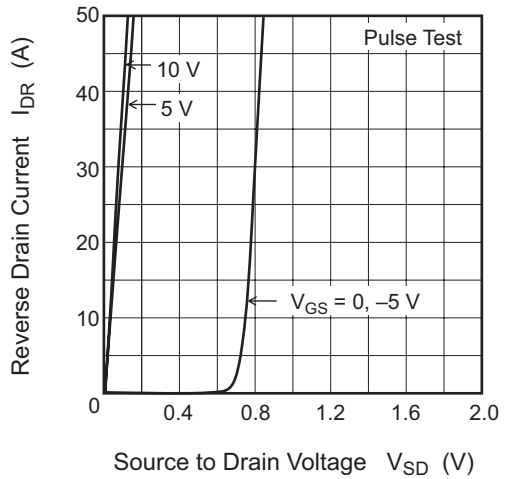
Typical Capacitance vs. Drain to Source Voltage



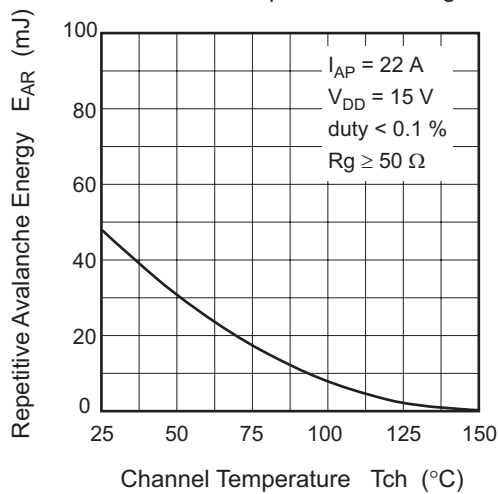
Dynamic Input Characteristics

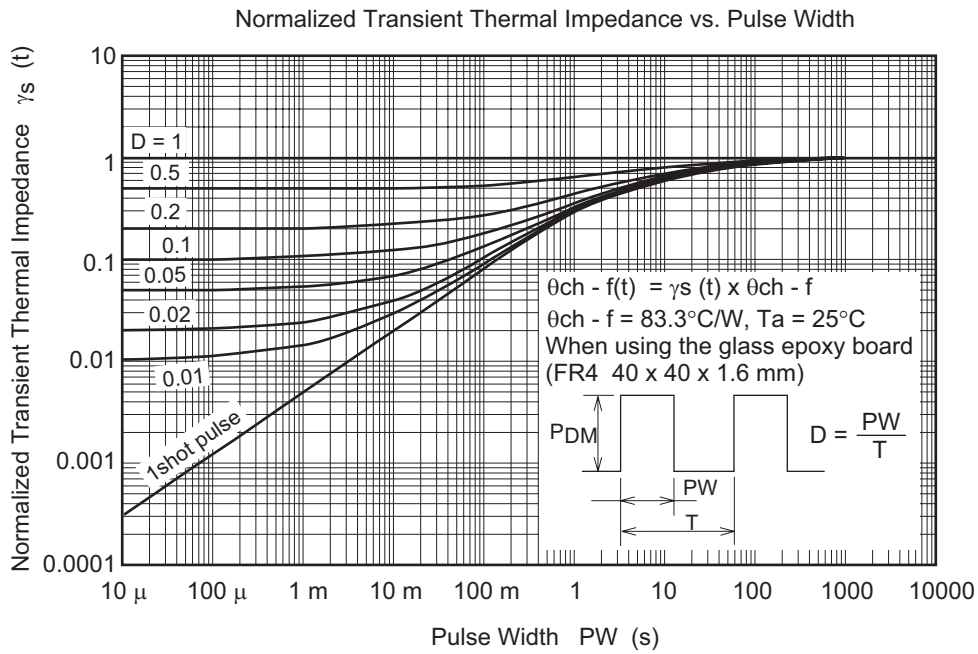


Reverse Drain Current vs. Source to Drain Voltage

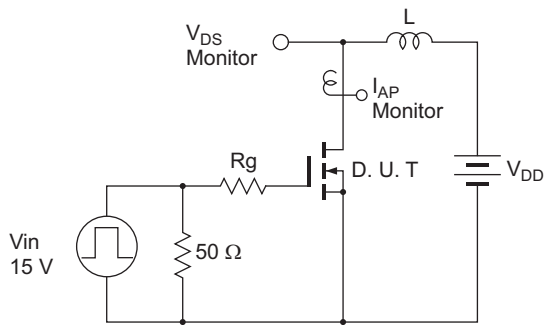


Maximum Avalanche Energy vs. Channel Temperature Derating



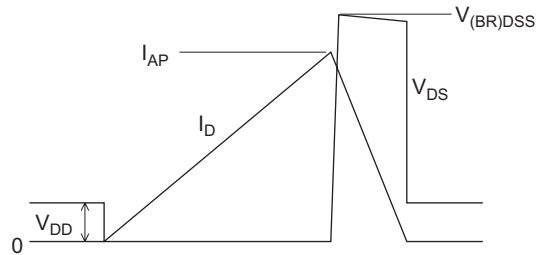


Avalanche Test Circuit

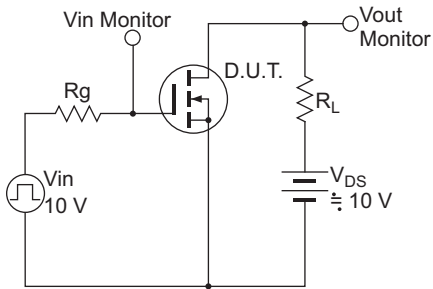


Avalanche Waveform

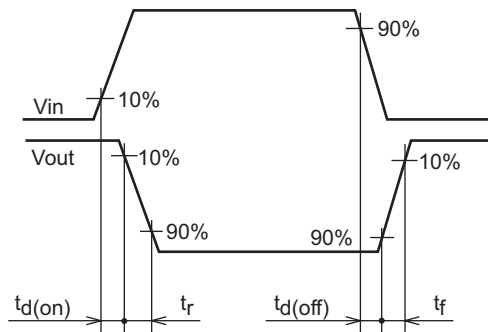
$$E_{AR} = \frac{1}{2} L \cdot I_{AP}^2 \cdot \frac{V_{DSS}}{V_{DSS} - V_{DD}}$$



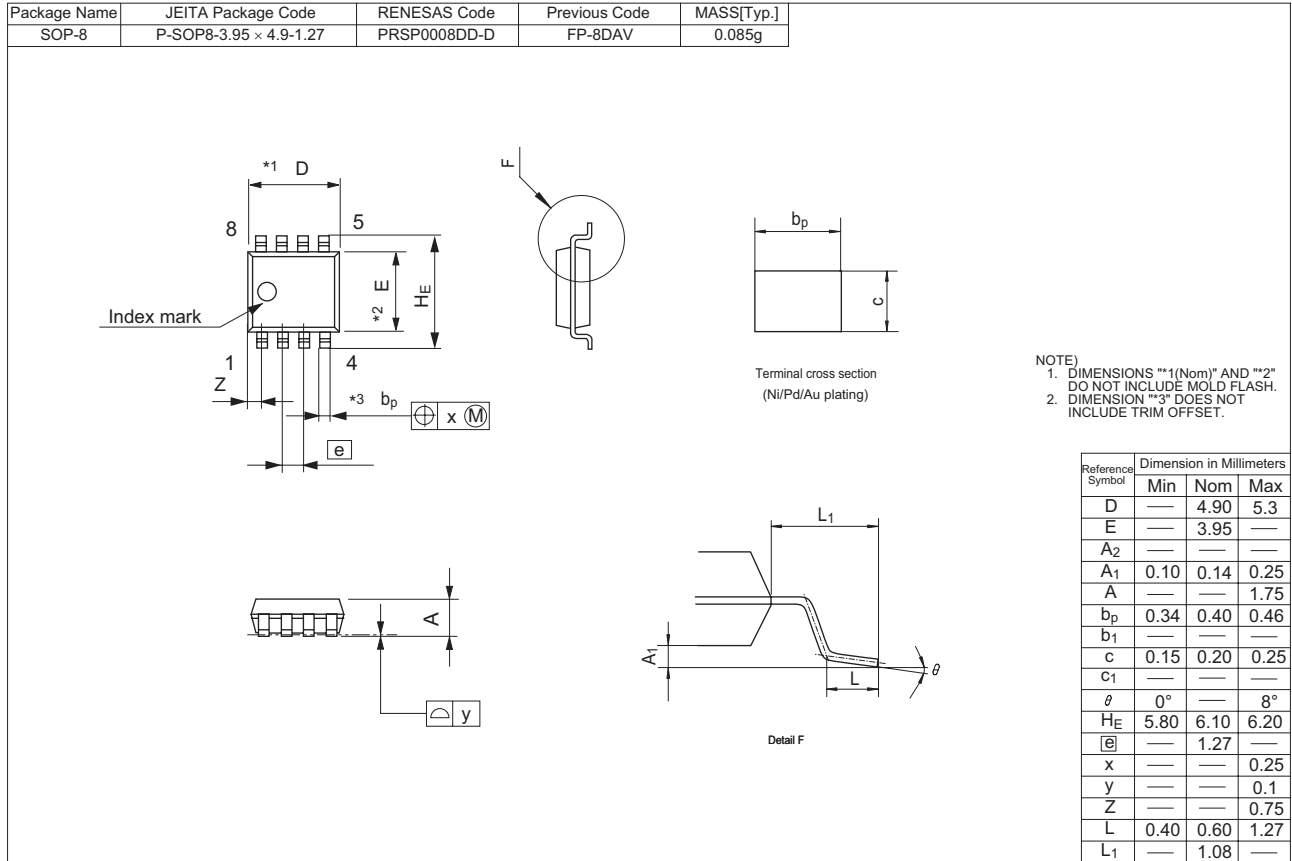
Switching Time Test Circuit



Switching Time Waveform



### Package Dimensions



### Ordering Information

Part No.	Quantity	Shipping Container
RJK0348DSP-00-J0	2500 pcs	Taping

Notes:

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